

a package frame comprising an aperture and a first surface, the first surface of the package frame comprising a package frame reference surface proximate the aperture, wherein the package frame reference surface is adapted to allow the die reference surface to be mounted to the package frame reference surface such that the optical micro-mechanical devices are located in the aperture;

one or more optical interconnect alignment mechanisms located on the first surface of the package frame and terminating adjacent to the aperture; and

distal ends of one or more optical interconnects located in the optical interconnect alignment mechanisms and optically coupled with one or more of the optical micro-mechanical devices.

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12. (Amended) A method of packaging optical micro-mechanical devices, comprising:

preparing a die comprising one or more optical micro-mechanical devices on a first surface of the die, the first surface of the die including a die reference surface;

attaching a tooling fixture to a second surface of the die;

preparing a package frame including an aperture and a first surface, the first surface of the package frame comprising a package frame reference surface proximate the aperture, wherein the package frame reference surface is adapted to allow the die reference surface to be mounted to the package frame reference surface such that the optical micro-mechanical devices are located in the aperture; and

preparing one or more optical interconnect alignment mechanisms on the first surface of the package frame, the optical interconnect alignment mechanisms on the package frame being positioned to align with corresponding optical micro-mechanical devices on the die when the die reference surface is mounted to the package frame reference surface.

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A version marked up to show changes made to the claims relative to the previous version of the claims is attached.

